AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

Claim 1 (Currently amended): Resin coated metal foil including an insulating resin composition layer and metal foil fixed to a single surface or both the surfaces of said insulating resin composition layer, wherein:

said insulating resin composition layer contains polyamidoimide resin and epoxy resin, ~~as principal ingredient,~~

surface treatment which is an anti-corrosive treatment using any one of nickel, tin, zinc, molybdenum, and cobalt or an alloy thereof, a chromate treatment and a silane coupling treatment is performed to at least an insulating resin composition layer side of said metal foil,

a thickness of said metal foil is not more than 3μm, and

roughening treatment is not substantially performed to both the surfaces of said metal foil.

Claim 2 (Original): The resin coated metal foil according to claim 1, characterized in that surface roughness (Rz) of said metal foil is not more than 2.0 μm in both the surfaces.

Claim 3 (Cancelled).

Claim 4 (Previously presented): The resin coated metal foil according to claim 1, characterized in that interfacial roughness (Rz) between said insulating resin composition layer and said metal foil is not more than 2.0 μm.

Claims 5-9. (Cancelled).

Claim 10 (Previously presented): The resin coated metal foil according to claim 1, characterized in that a silane coupling agent used for said silane coupling treatment chemically reacts with said insulating resin composition by heating.

Claims 11 and 12. (Cancelled).

Claim 13 (Previously presented): The resin coated metal foil according to claim 1, characterized in that said insulating resin composition contains epoxy resin which is liquid at room temperatures.

Claim 14 (Cancelled).

Claim 15 (Previously presented): The resin coated metal foil according to claim 1, characterized in that, in said post-cure insulating resin composition, a relative dielectric constant is not more than 3.0 at 1 GHz or a dielectric loss tangent is not more than 0.01 at 1 GHz.

Claim 16 (Currently amended): A metal clad laminate including an insulating

resin composition layer and metal foil fixed to a single surface or both the surfaces of said insulating resin composition layer, wherein:

said insulating resin composition layer contains polyamidoimide resin and epoxy resin, ~~as principal ingredient,~~

surface treatment which is an anti-corrosive treatment using any one of nickel, tin, zinc, molybdenum, and cobalt or an alloy thereof, a chromate treatment and a silane coupling treatment is performed to at least an insulating resin composition layer side of said metal foil,

a thickness of said metal foil is not more than 3μm, and

roughening treatment is not substantially performed to both the surfaces of said metal foil.

Claim 17 (Original): The metal clad laminate according to claim 16, characterized in that surface roughness (Rz) of said metal foil is not more than 2.0 μm in both the surfaces.

Claim 18 (Cancelled).

Claim 19 (Previously presented): The metal clad laminate according to claim 16 , characterized in that interfacial roughness (Rz) between said insulating resin composition layer and said metal foil is not more than 2.0 μm.

Claims 20-24. (Cancelled).

Claim 25 (Previously presented): The metal clad laminate according to claim 16, characterized in that a silane coupling agent used for said silane coupling treatment chemically reacts with said insulating resin composition by heating.

Claims 26 and 27. (Cancelled).

Claim 28 (Previously presented): The metal clad laminate according to claim 16, characterized in that said insulating resin composition contains epoxy resin which is liquid at room temperatures.

Claim 29 (Cancelled).

Claim 30 (Previously presented): The metal clad laminate according to claim 16, characterized in that, in said post-cure insulating resin composition, a relative dielectric constant is not more than 3.0 at 1 GHz or a dielectric loss tangent is not more than 0.01 at 1 GHz.

Claim 31 (Previously presented): A printed wiring board characterized by being manufactured with resin coated metal foil according to claim 1.

Claim 32 (Original): The printed wiring board according to claim 31, characterized in that surface roughness (Rz) of a conductor circuit is not more than 2.0 μm.

Claim 33 (Previously presented): The printed wiring board according to claim 31, characterized in that peel strength between said insulating resin composition layer and a conductor circuit having a width of 1 mm is not lower than 0.6 kN/m.

Claim 34 (Previously presented): The printed wiring board according to claim 31, characterized in that the peel strength between said insulating resin composition layer that has been heated at 150°C for 240 hours and the conductor circuit having the width of 1 mm is not lower than 0.4 kN/m.

Claims 35–40. (Cancelled).

Claim 41 (Previously presented): A printed wiring board characterized by being manufactured with a metal clad laminate according to claim 16.

Claim 42 (Previously presented): The printed wiring board according to claim 41, characterized in that surface roughness (Rz) of a conductor circuit is not more than 2.0 μm.

Claim 43 (Previously presented): The printed wiring board according to claim 41, characterized in that peel strength between said insulating resin composition layer and a conductor circuit having a width of 1 mm is not lower than 0.6 kN/m.

Claim 44 (Previously presented): The printed wiring board according to claim 41, characterized in that the peel strength between said insulating resin composition layer that has been heated at 150°C for 240 hours and the conductor circuit having the width of 1 mm is not lower than 0.4 kN/m.

Claims 45 – 50. (Cancelled).

Claim 51 (Previously presented): The resin coated metal foil according to claim 2, wherein the surface roughness (Rz) of said metal foil is not more than 1.5 μm in both the surfaces.

Claim 52 (Previously presented): The resin coated metal foil according to claim 2, wherein the surface roughness (Rz) of said metal foil is not more than 1.0 μm in both the surfaces.

Claim 53 (Previously presented): The resin coated metal foil according to claim 1, wherein the metal foil is a copper foil.

Claim 54 (Previously presented): The metal clad laminate according to claim 16, wherein the metal foil is a copper foil.

Claim 55 (Previously presented): The resin coated metal foil according to claim 1, wherein said polyamidoimide resin is siloxane denatured polyamidoimide resin.

Claims 56-63. (Cancelled).

Claim 64 (New): The metal clad laminate according to claim 16, wherein said polyamidoimide resin is siloxane denatured polyamidoimide resin.

Claim 65 (New): The resin coated metal foil according to claim 55, wherein said siloxane denatured polyamidoimide resin has a molecular weight not lower than 50,000.

Claim 66 (New): The metal clad laminate to claim 64, wherein said siloxane denatured polyamidoimide resin has a molecular weight not lower than 50,000.